3/15/04	USPAT: US-PGPUB: FPO: JPO: DERWENT: IBM TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	EPO; JPO; DERWENT;	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	DERWENT; IBM	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	EPO; JPO; DERWENT;	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	JPO; DERWENT; IBM_	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	DERWENT; IBM_	DERWENT; IBM	DERWENT; IBM	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB														
	1ts Search String 2 5835 379 no	2 4,387,655.pn.	2 4,504,920.pn.	2 4,534,003.pn.	2 4,868,751.pn.	2 4,989,166.pn.	2 5,031,108.pn.	2 5,031,127.pn.	2 5,035,598.pn.	2 5,097,431.pn.	2 5,097,432.pn.		2 5,350,547,pn.		2 5,549,857,pn.		2 5,811,133.pn.	2 5,581,468.pn.	2 Niigata Engineering and Miyoshi and "injection molding"	Toray Industries and Nakano and "injec	_	Kamiguchi and "position of resin"		0 92902748 and CAVITY	2 3,977,255.pn.	2 4,641,270.pn.			2 6,021,270.pn.	2 6,096,088.pn.	2 6,192,327.pn.	2 6,327,553.pn.	78 injection molding with simulat\$	191 injection molding with model\$	044 1 or 2
1		2	2	2	7	7	7	7	7	7	7	7	7	7	2	7	2	7	7	9	0	0	0	0	7	7	7	7	7	7	7	2	178	891	1044
*	2	ខា	4	L5	۲۷	F3	L10	L11	L12	L13	7	L 3	L 4	L 5	97	F8	۲۷	F3	L10	L11										L10	7	L12	2	7	ยา

12 18 18	29 15 277 16	3 and (model\$ with three-dimensional) 1 and (three-dimensional) injection with mold\$3 with simulat\$3 7 and (three-dimensional)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	10 4 4 14 0 0 8 8	6,096,088.pn. or 5,581,468.pn. or 5,572,434.pn. or 5,811,133.pn. or 5,835,379.pn. 5,900,259.pn. or 5,377,119.pn. 2 or 3 4 and (component with (mass or volume or density)) injection with mold\$3 with simulat\$3 6 and (component with (mass or volume or density)) 6 and (component same (mass or volume or density))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
	2181 5 108 108 13 0 0 83 45	thermal diffusivity thermal diffusivity and "peclet number" ("thermal diffusivity and "error function") and ("thermal diffusivity" and "error function" thermal diffusivity and "error function" thermal diffusivity and "injection molding" ("thermal diffusivity" and "injection molding") and "finite element" ("thermal diffusivity" and "injection molding") and (conservation with energy) thermal diffusivity and "finite element" thermal diffusivity and "finite element" ("thermal diffusivity and "finite element") thermal diffusivity and "finite element") ("thermal diffusivity and "thermal clock")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
L1 L3 L4 L5 L6 L8 L7 L9	336 2 2 2 10 10 10 10 10 10 10 10 10 10 10 10 10 1	thermal diffusivity and ("peclet number") temperature convection thermal clock 2 and (conservation adj energy) 2 and (conserv\$5 with energy) injection molding and ("peclet number") 7 and (energy with (conserv\$5 or equation)) advection and "peclet number" advection and (energy with (conserv\$5 or equation)) Christian FriedI et al.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

EAST SEARCH

3/15/04

Results of search set L5:(injection molding with (simulats or model\$3)) and (model\$ with three-dimensional)

Abstract
ssue Date Current OR 20020829 345/771 20020620 434/277 20020620 434/277 20011122 623/1.16 20030429 75/228 20030204 700/200 20021029 434/278 20020917 228/110.1 20020917 228/110.1 20020917 228/110.1 20000411 526/328.5 19990907 434/278 19990907 434/278 19990907 434/278 19990907 128/898 19920317 700/197 19970819 128/898 19920317 703/9 19911210 264/1.34 19800520 446/61 20020604 200000808 20000111 19950930
Inflementation processing apparatus and method Tool and process for casting a shaped part for the production of a turbine blade Molecular models Expandable stent with sliding and locking radial elements Expandable stent with sliding and compositions therefor System and method for mapping a surface Multiple-material prototyping by ultrasonic adhesion Model of complex structure and method of making the same Multiple-material prototyping by ultrasonic adhesion Model of complex structure and method of making the same Multiple-material prototyping by ultrasonic adhesion Multiple-material prototyping by ultrasonic adhesion Apparatus for analyzing a process of fluid flow, and a production method of an injection molded Binder compositions for laser sintering processes Atomic model of simultaneous electron-pair-sharing and allosterism Implantable articles with as-cast macrotextured surface regions and method of manufacturing Apparatus and method for analyzing a process of fluid flow, an apparatus and method of manufacturing Implantable articles with as-cast macrotextured surface regions and method of manufacturing Production of three dimensional bodies by photopolymerization Evaluation method of flow analysis on molding of a motten material Pastic molding of articles including a hologram or other microstructure Molded model airplane METHOD AND AND APPARATUS FOR MOLDING THREE-DIMENSIONAL SHAPE OF MOLDED PORTRAIT MODEL AND MANUFACTURE THEREFOR MILLECTION MOLDING PROCESS SIMULATION SYSTEM PLAN SUPPORT APPARATUS DEVICE AND METHOD FOR ANALYSIS OF FLUID FLOWING PROCESS, DEVICE AND ME An apparatus and method for analyzing a process of fluid flow, an apparatus and method for analyzing a process of fluid flow, an apparatus and method for analyzing a process of fluid flow, an apparatus and method for analyzing a process of fluid flow, an apparatus and method for analyzing a process of fluid flow, an apparatus and method for analyzing a process of fluid flow, an anapparatus and method for analyzing a proc
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